

Circuit Bond Epoxy

Instruction: INS1063

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115-3302 Circuit Bond Epoxy is a clear, low viscosity, superior strength epoxy, precisely measured out into two-compartment plastic packages so it's easy to use and there's no measuring.

Once cured, this epoxy makes an effective electrical insulator with good high temperature, mechanical and impact resistance properties. Circuit Bond can be used to bond replacement conductors, repair burns and circuit board surface defects, and many other high strength, high temperature applications.



You can also tint Circuit Bond using Color Agents for the perfect cosmetic match. See guides covering a variety of repair and rework applications at www.circuitrework.com/guides/guides.html.

Specifications	
Packaging	2 gram pre-measured packages
Mix ratio	4 parts resin to 1 part hardener
Mix Ratio by Weight (R/H)	100/25
Color	Clear, transparent
Pot life	30 minutes
Cure cycle	24 hours at room temperature (25 °C) or 4 hours @ 65°C
Thixotropic Index	1
Specific Gravity	1.20
Percent Solids	100%
Viscosity (after mixing)	2000 cps
Operating temperature range	-55°C to 135°C
Hardness	88 Shore D
Lap Shear, Alum to Alum	1100 psi
Glass Transition Temperature, Ultimate	92°C
Coefficient of Expansion, cm/cm/°C	6 E-05
Dielectric strength	400 volts/mil
Dielectric Constant, 1KHz@25°C	4
Shelf Life	6 months minimum

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Application Instructions

1. Circuit Bond has a working pot life of 30 minutes. It should not be mixed until ready to use.
2. To use Circuit Bond, remove the plastic clip separating the resin and hardener. Squeeze back and forth from one half of the package to the other to mix the contents.
3. Cut a corner off the package and squeeze all the contents into a Plastic Cup. Stir the contents to ensure it is thoroughly mixed.
4. NOTE: Circuit Bond may contain bubbles from the mixing process. If needed use a vacuum system to remove bubbles.
5. If desired Color Agent can be mixed in with Circuit Bond to match surface colors.
6. Apply using a Foam Swab, Micro Probe or Mixing Stick as required.
7. Cure Circuit Bond for 24 hours at room temperature or 4 hours at 65°C (150°F).